

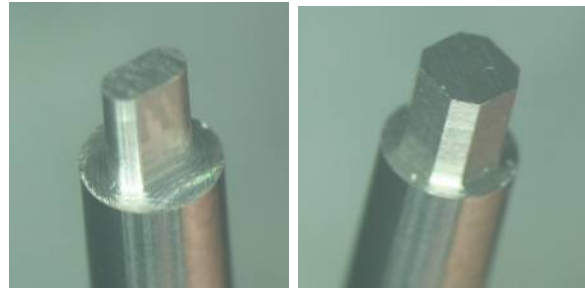
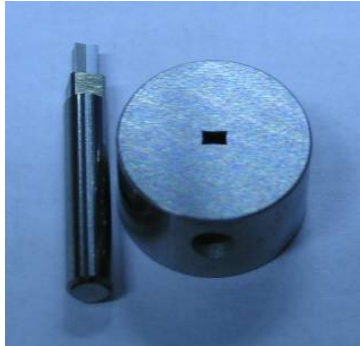


サンプル Sample

1. 金型 Press Mold

試作型 Trial Punch & Die

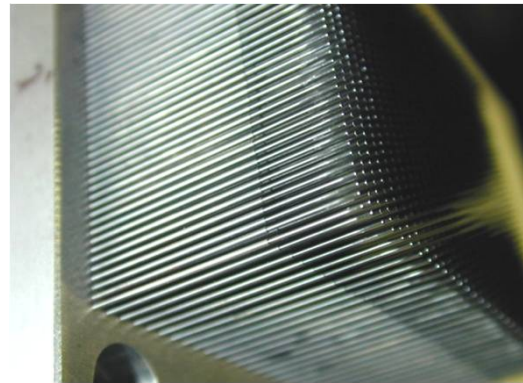
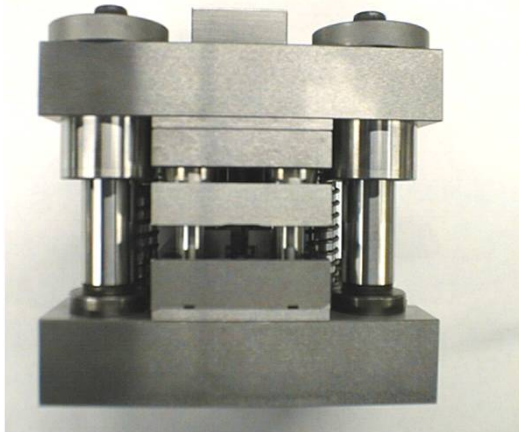
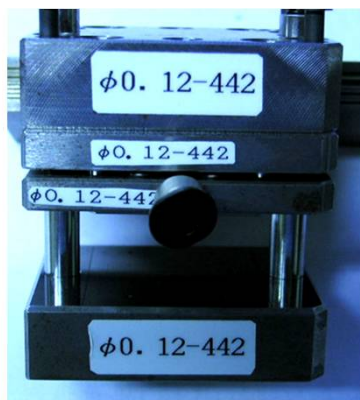
単ピン Single Punch



試作型 Trial Punch & Die

多ピン Multi Punch

442-φ0.12



量産型 Mass production Press Mold

量産型 Mass production Press Mold

・穴あけ Punching holes

小径穴 Small holes : 量産 Mass production φ0.07

試作 Trial φ0.03

多数穴 Multi holes : >10000穴 Holes

・ブレイク溝の同時形成 Form Break line at the same time

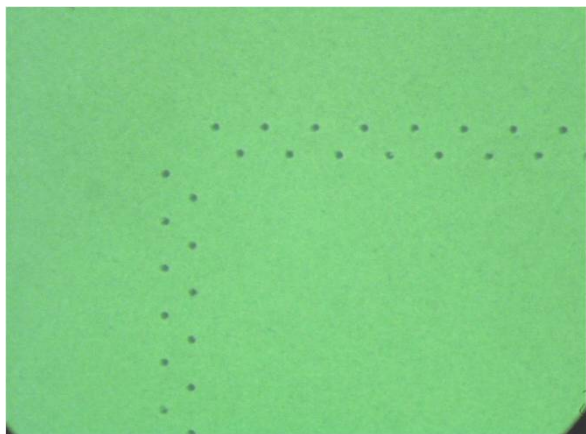
縦・横一体成形 Form vertical and horizontal Break line at one time

2工程仕様 Divide forming vertical and horizontal Break line

ブレイク溝上に穴をあけることも可能です

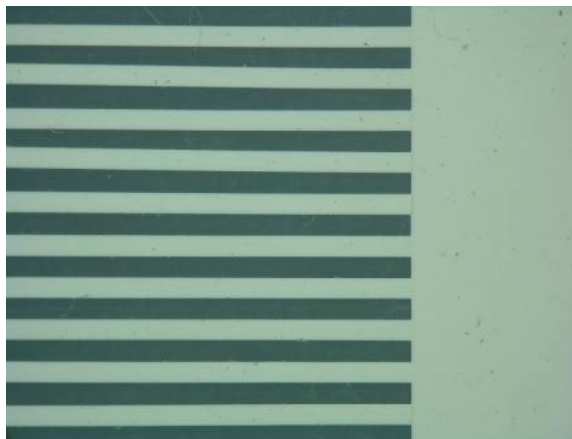
Makeing holes on the break line is possible

2. 抜きサンプル Pressed Samples



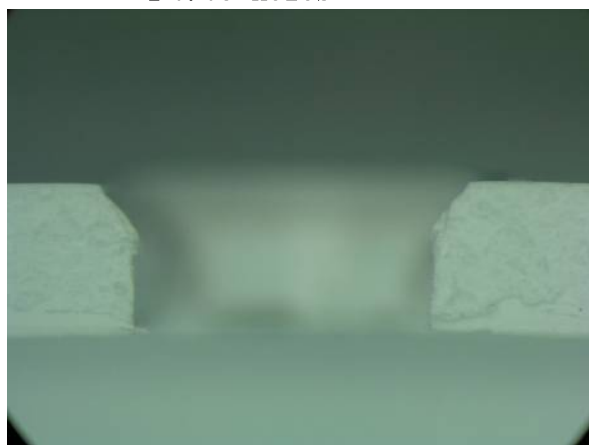
小径穴 Small holes

$\Phi 0.03$ holes



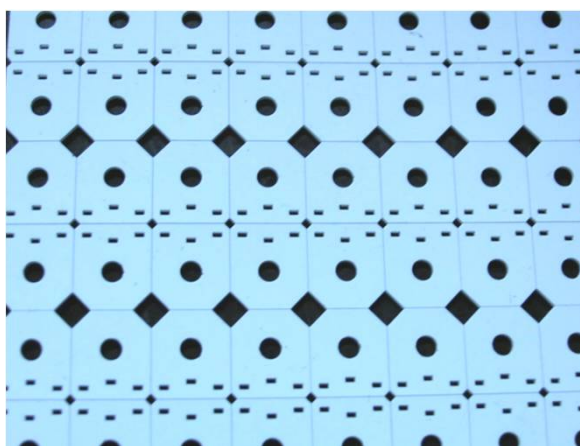
幅0.3 スリットと溝

0.3 width Slits & Bridges

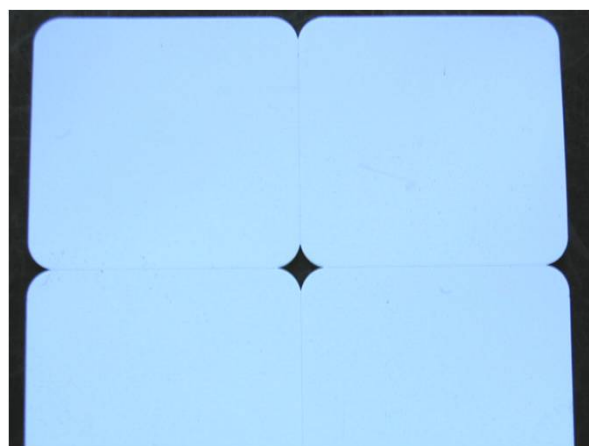


穴にC面付け

Chanfer at punched hole

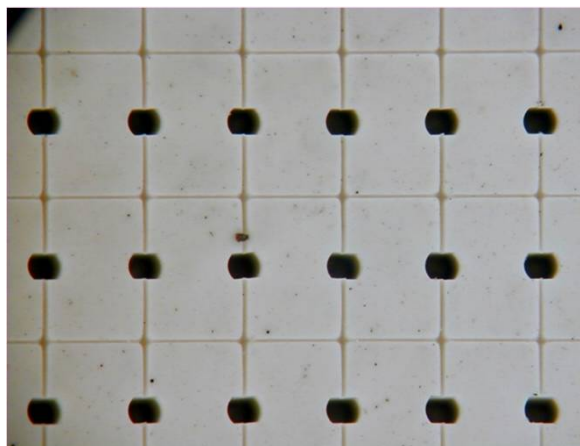


ボリューム基板 Volume substrate



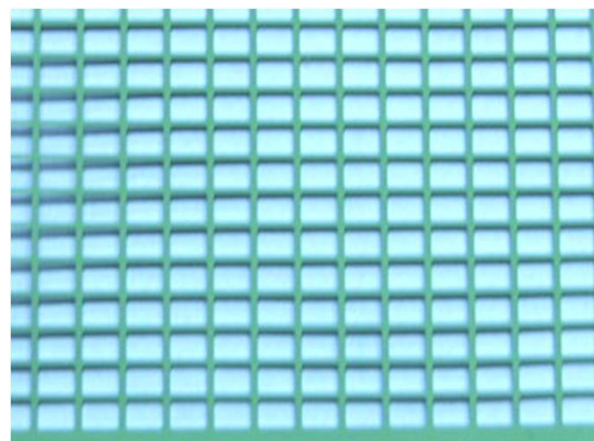
パワー素子基板

Power device substrate



チップ抵抗基板

Chip resistor substrate
0.18×0.24角穴 と ブレーク溝



積層パッケージ基板

Lamination package

↑
↑
1つ上
トップ